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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	e200z4d
Core Size	32-Bit Dual-Core
Speed	120MHz
Connectivity	CANbus, LINbus, SCI, SPI, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	57
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.63V
Data Converters	A/D 32x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/spc56el60l3cbfsy

3.13 Main oscillator electrical characteristics 116
3.14 FMPLL electrical characteristics 118
3.15 16 MHz RC oscillator electrical characteristics 119
3.16 ADC electrical characteristics 119
3.16.1 Input Impedance and ADC Accuracy 120
3.17 Flash memory electrical characteristics 125
3.18 SWG electrical characteristics 127
3.19 AC specifications 127
3.19.1 Pad AC specifications 127
3.20 Reset sequence 128
3.20.1 Reset sequence duration 128
3.20.2 Reset sequence description 129
3.20.3 Reset sequence trigger mapping 131
3.20.4 Reset sequence — start condition 132
3.20.5 External watchdog window 134
3.21 AC timing characteristics 134
3.21.1 RESET pin characteristics 134
3.21.2 WKUP/NMI timing 136
3.21.3 IEEE 1149.1 JTAG interface timing 136
3.21.4 Nexus timing 138
3.21.5 External interrupt timing (IRQ pin) 141
3.21.6 DSPI timing 142

4 Package characteristics 148
4.1 ECOPACK® 148
4.2 Package mechanical data 148

5 Ordering information 153

6 Revision history 154

1 Introduction

1.1 Document overview

This document describes the features of the family and options available within the family members, and highlights important electrical and physical characteristics of the devices.

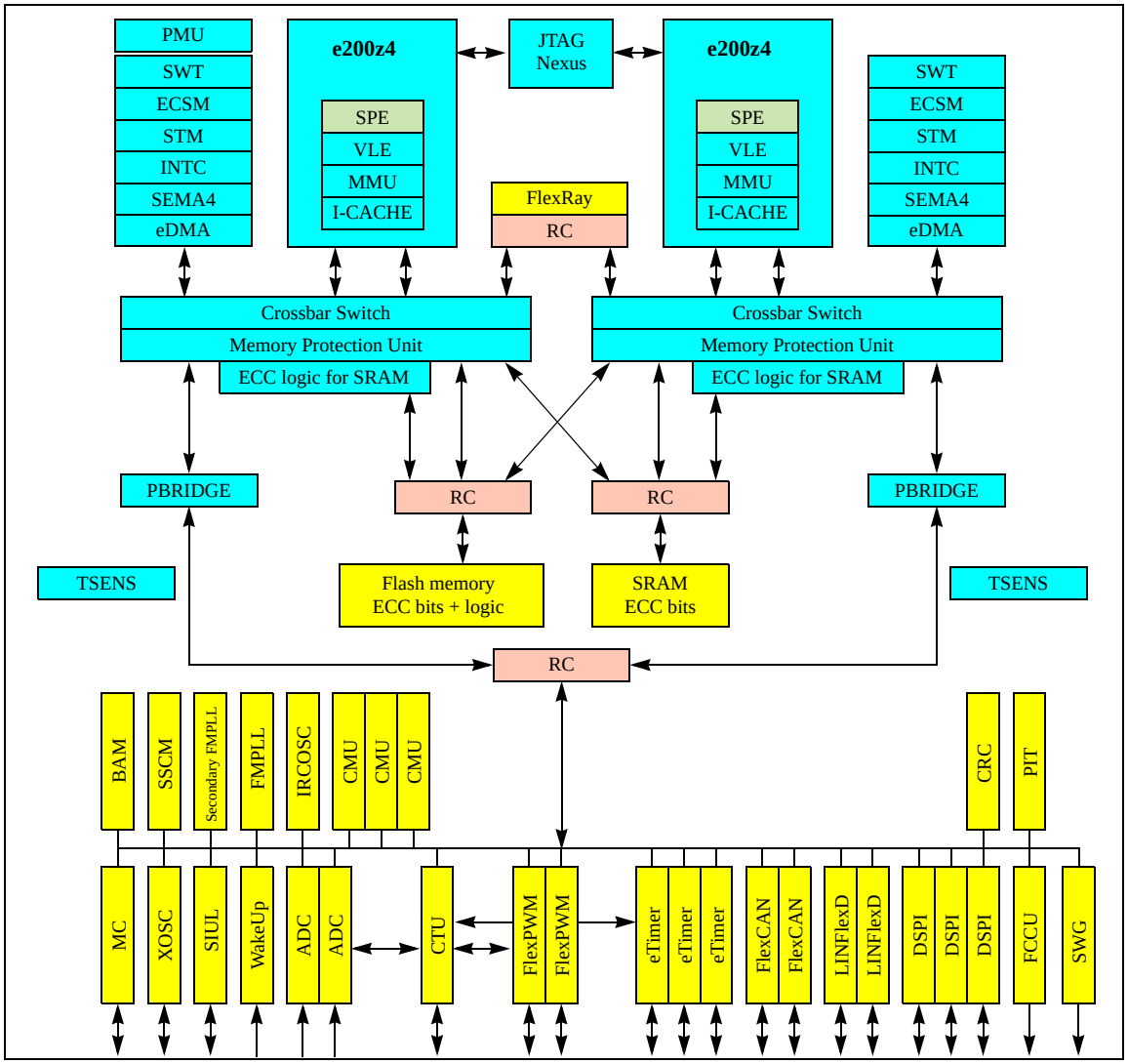
This document provides electrical specifications, pin assignments, and package diagrams for the SPC56ELx/SPC564Lx series of microcontroller units (MCUs). For functional characteristics, see the *SPC56ELx/SPC564Lx Microcontroller Reference Manual*. For use of the SPC56ELx/SPC564Lx in a fail-safe system according to safety standard ISO26262, see the *Safety Application Guide for SPCEL60.*

1.2 Description

The SPC56ELx/SPC564Lx series microcontrollers are system-on-chip devices that are built on Power Architecture technology and contain enhancements that improve the architecture's fit in embedded applications, include additional instruction support for digital signal processing (DSP) and integrate technologies such as an enhanced time processor unit, enhanced queued analog-to-digital converter, Controller Area Network, and an enhanced modular input-output system.

The SPC56ELx/SPC564Lx family of 32-bit microcontrollers is the latest achievement in integrated automotive application controllers. It belongs to an expanding range of automotive-focused products designed to address electrical hydraulic power steering (EHPS), electric power steering (EPS) and airbag applications. The advanced and cost-efficient host processor core of the SPC56ELx/SPC564Lx automotive controller family complies with the Power Architecture embedded category. It operates at speeds as high as 120 MHz and offers high-performance processing optimized for low power consumption. It capitalizes on the available development infrastructure of current Power Architecture devices and is supported with software drivers, operating systems and configuration code to assist with users' implementations.

Figure 1. SPC56ELx/SPC564Lx block diagram



ADC – Analog-to-Digital Converter
BAM – Boot Assist Module
CMU – Clock Monitoring Unit
CRC – Cyclic Redundancy Check unit
CTU – Cross Triggering Unit
DSPI – Serial Peripherals Interface
ECC – Error Correction Code
ECSM – Error Correction Status Module
eDMA – Enhanced Direct Memory Access controller
FCCU – Fault Collection and Control Unit
FlexCAN – Controller Area Network controller
FMPLL – Frequency Modulated Phase Locked Loop
INTC – Interrupt Controller
IRCOSC – Internal RC Oscillator
JTAG – Joint Test Action Group interface
LINFlexD – LIN controller with DMA support
MC – Mode Entry, Clock, Reset, & Power
PBRIDGE – Peripheral bridge
PIT – Periodic Interrupt Timer
PMU – Power Management Unit
RC – Redundancy Checker
RTC – Real Time Clock
SEMA4 – Semaphore Unit
SIUL – System Integration Unit Lite
SSCM – System Status and Configuration Module
STM – System Timer Module
SWG – Sine Wave Generator
SWT – Software Watchdog Timer
TSENS – Temperature Sensor
XOSC – Crystal Oscillator

- Extensive system development and tracing support via Nexus debug port

1.5.2 Crossbar switch (XBAR)

The XBAR multi-port crossbar switch supports simultaneous connections between four master ports and three slave ports. The crossbar supports a 32-bit address bus width and a 64-bit data bus width.

The crossbar allows four concurrent transactions to occur from any master port to any slave port, although one of those transfers must be an instruction fetch from internal flash memory. If a slave port is simultaneously requested by more than one master port, arbitration logic selects the higher priority master and grants it ownership of the slave port. All other masters requesting that slave port are stalled until the higher priority master completes its transactions.

The crossbar provides the following features:

- 4 masters and 3 slaves supported per each replicated crossbar
  - Masters allocation for each crossbar: e200z4d core with two independent bus interface units (BIU) for I and D access (2 masters), one eDMA, one FlexRay
  - Slaves allocation for each crossbar: a redundant flash-memory controller with 2 slave ports to guarantee maximum flexibility to handle Instruction and Data array, one redundant SRAM controller with 1 slave port each and 1 redundant peripheral bus bridge
- 32-bit address bus and 64-bit data bus
- Programmable arbitration priority
  - Requesting masters can be treated with equal priority and are granted access to a slave port in round-robin method, based upon the ID of the last master to be granted access or a priority order can be assigned by software at application run time
- Temporary dynamic priority elevation of masters

The XBAR is replicated for each processing channel.

1.5.3 Memory Protection Unit (MPU)

The Memory Protection Unit splits the physical memory into 16 different regions. Each master (eDMA, FlexRay, CPU) can be assigned different access rights to each region.

- 16-region MPU with concurrent checks against each master access
- 32-byte granularity for protected address region

The memory protection unit is replicated for each processing channel.

1.5.4 Enhanced Direct Memory Access (eDMA)

The enhanced direct memory access (eDMA) controller is a second-generation module capable of performing complex data movements via 16 programmable channels, with minimal intervention from the host processor. The hardware micro architecture includes a DMA engine which performs source and destination address calculations, and the actual data movement operations, along with an SRAM-based memory containing the transfer control descriptors (TCD) for the channels. This implementation is used to minimize the overall block size.

The CTU implements the following features:

- Cross triggering between ADC, FlexPWM, eTimer, and external pins
- Double buffered trigger generation unit with as many as 8 independent triggers generated from external triggers
- Maximum operating frequency less than or equal to 120 MHz
- Trigger generation unit configurable in sequential mode or in triggered mode
- Trigger delay unit to compensate the delay of external low pass filter
- Double buffered global trigger unit allowing eTimer synchronization and/or ADC command generation
- Double buffered ADC command list pointers to minimize ADC-trigger unit update
- Double buffered ADC conversion command list with as many as 24 ADC commands
- Each trigger capable of generating consecutive commands
- ADC conversion command allows control of ADC channel from each ADC, single or synchronous sampling, independent result queue selection
- DMA support with safety features

1.5.35 Cyclic Redundancy Checker (CRC) Unit

The CRC module is a configurable multiple data flow unit to compute CRC signatures on data written to its input register.

The CRC unit has the following features:

- 3 sets of registers to allow 3 concurrent contexts with possibly different CRC computations, each with a selectable polynomial and seed
- Computes 16- or 32-bit wide CRC on the fly (single-cycle computation) and stores result in internal register.
  The following standard CRC polynomials are implemented:
  - $x^8 + x^4 + x^3 + x^2 + 1$ [8-bit CRC]
  - $x^{16} + x^{12} + x^5 + 1$ [16-bit CRC-CCITT]
  - $x^{32} + x^{26} + x^{23} + x^{22} + x^{16} + x^{12} + x^{11} + x^{10} + x^8 + x^7 + x^5 + x^4 + x^2 + x + 1$ [32-bit CRC-ethernet(32)]
- Key engine to be coupled with communication periphery where CRC application is added to allow implementation of safe communication protocol
- Offloads core from cycle-consuming CRC and helps checking configuration signature for safe start-up or periodic procedures
- CRC unit connected as peripheral bus on internal peripheral bus
- DMA support

1.5.36 Redundancy Control and Checker Unit (RCCU)

The RCCU checks all outputs of the sphere of replication (addresses, data, control signals). It has the following features:

- Duplicated module to guarantee highest possible diagnostic coverage (check of checker)
- Multiple times replicated IPs are used as checkers on the SoR outputs

2 Package pinouts and signal descriptions

2.1 Package pinouts

Figure 2 shows the LQFP100 pinout.

Figure 2. LQFP100 pinout

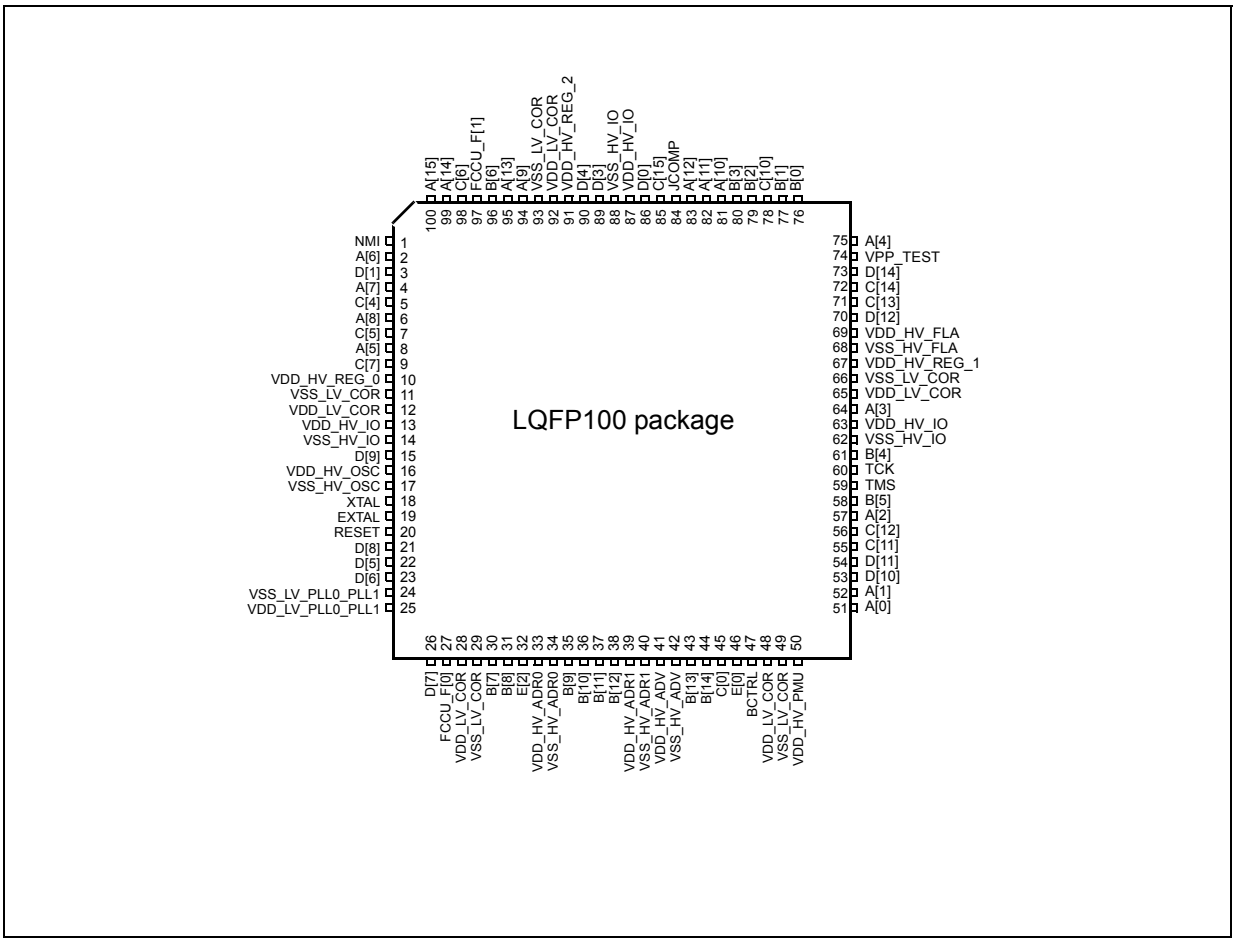


Figure 3 shows the SPC56ELx/SPC564Lx in the LQFP144 package.

Table 4. LQFP144 pin function summary (continued)

Pin #	Port/function	Peripheral	Output function	Input function
15	C[7]	SIUL	GPIO[39]	GPIO[39]
		FlexPWM_0	A[1]	A[1]
		SSCM	DEBUG[7]	—
		DSPI_0	—	SIN
16	$V_{DD\_HV\_REG\_0}$	—		
17	$V_{SS\_LV\_COR}$	—		
18	$V_{DD\_LV\_COR}$	—		
19	F[7]	SIUL	GPIO[87]	GPIO[87]
		NPC	MCKO	—
20	F[8]	SIUL	GPIO[88]	GPIO[88]
		NPC	MSEO[1]	—
21	$V_{DD\_HV\_IO}$	—		
22	$V_{SS\_HV\_IO}$	—		
23	F[9]	SIUL	GPIO[89]	GPIO[89]
		NPC	MSEO[0]	—
24	F[10]	SIUL	GPIO[90]	GPIO[90]
		NPC	EVTO	—
25	F[11]	SIUL	GPIO[91]	GPIO[91]
		NPC	—	EVTI
26	D[9]	SIUL	GPIO[57]	GPIO[57]
		FlexPWM_0	X[0]	X[0]
		LINFlexD_1	TXD	—
27	$V_{DD\_HV\_OSC}$	—		
28	$V_{SS\_HV\_OSC}$	—		
29	XTAL	—		
30	EXTAL	—		
31	RESET	—		
32	D[8]	SIUL	GPIO[56]	GPIO[56]
		DSPI_1	CS2	—
		eTimer_1	ETC[4]	ETC[4]
		DSPI_0	CS5	—
		FlexPWM_0	—	FAULT[3]
33	D[5]	SIUL	GPIO[53]	GPIO[53]
		DSPI_0	CS3	—
		FlexPWM_0	—	FAULT[2]

Table 4. LQFP144 pin function summary (continued)

Pin #	Port/function	Peripheral	Output function	Input function
108	A[4]	SIUL	GPIO[4]	GPIO[4]
		eTimer_1	ETC[0]	ETC[0]
		DSPI_2	CS1	—
		eTimer_0	ETC[4]	ETC[4]
		MC_RGM	—	FAB
		SIUL	—	EIRQ[4]
109	B[0]	SIUL	GPIO[16]	GPIO[16]
		FlexCAN_0	TXD	—
		eTimer_1	ETC[2]	ETC[2]
		SSCM	DEBUG[0]	—
		SIUL	—	EIRQ[15]
110	B[1]	SIUL	GPIO[17]	GPIO[17]
		eTimer_1	ETC[3]	ETC[3]
		SSCM	DEBUG[1]	—
		FlexCAN_0	—	RXD
		FlexCAN_1	—	RXD
		SIUL	—	EIRQ[16]
111	C[10]	SIUL	GPIO[42]	GPIO[42]
		DSPI_2	CS2	—
		FlexPWM_0	A[3]	A[3]
		FlexPWM_0	—	FAULT[1]
112	F[13]	SIUL	GPIO[93]	GPIO[93]
		eTimer_1	ETC[4]	ETC[4]
		SIUL	—	EIRQ[31]
113	F[15]	SIUL	GPIO[95]	GPIO[95]
		LINFlexD_1	—	RXD
114	B[2]	SIUL	GPIO[18]	GPIO[18]
		LINFlexD_0	TXD	—
		SSCM	DEBUG[2]	—
		SIUL	—	EIRQ[17]
115	F[14]	SIUL	GPIO[94]	GPIO[94]
		LINFlexD_1	TXD	—
116	B[3]	SIUL	GPIO[19]	GPIO[19]
		SSCM	DEBUG[3]	—
		LINFlexD_0	—	RXD

Table 5. LFBGA257 pin function summary (continued)

Pin #	Port/function	Peripheral	Output function	Input function
G14	D[12]	SIUL	GPIO[60]	GPIO[60]
		FlexPWM_0	X[1]	X[1]
		LINFlexD_1	—	RXD
G15	H[13]	SIUL	GPIO[125]	GPIO[125]
		FlexPWM_1	X[3]	X[3]
		eTimer_2	ETC[3]	ETC[3]
G16	H[9]	SIUL	GPIO[121]	GPIO[121]
		FlexPWM_1	B[1]	B[1]
		DSPI_0	CS7	—
G17	G[6]	SIUL	GPIO[102]	GPIO[102]
		FlexPWM_0	A[3]	A[3]
H1	G[13]	SIUL	GPIO[109]	GPIO[109]
		NPC	MDO[10]	—
H2	$V_{SS\_HV\_IO\_RING}$	—		
H3	C[4]	SIUL	GPIO[36]	GPIO[36]
		DSPI_0	CS0	CS0
		FlexPWM_0	X[1]	X[1]
		SSCM	DEBUG[4]	—
		SIUL	—	EIRQ[22]
H4	A[5]	SIUL	GPIO[5]	GPIO[5]
		DSPI_1	CS0	CS0
		eTimer_1	ETC[5]	ETC[5]
		DSPI_0	CS7	—
		SIUL	—	EIRQ[5]
H6	V_{DD_LV}	—		
H7	V_{SS_LV}	—		
H8	V_{SS_LV}	—		
H9	V_{SS_LV}	—		
H10	V_{SS_LV}	—		
H11	V_{SS_LV}	—		
H12	V_{DD_LV}	—		
H14	V_{SS_LV}	—		
H15	$V_{DD\_HV\_REG\_1}$	—		
H16	$V_{DD\_HV\_FLA}$	—		

Table 5. LFBGA257 pin function summary (continued)

Pin #	Port/function	Peripheral	Output function	Input function
L16	H[4]	SIUL	GPIO[116]	GPIO[116]
		FlexPWM_1	X[0]	X[0]
		eTimer_2	ETC[0]	ETC[0]
L17	B[4]	SIUL	GPIO[20]	GPIO[20]
		JTAGC	TDO	—
M1	$V_{DD\_HV\_OSC}$	—		
M2	$V_{DD\_HV\_IO\_RING}$	—		
M3	D[8]	SIUL	GPIO[56]	GPIO[56]
		DSPI_1	CS2	—
		eTimer_1	ETC[4]	ETC[4]
		DSPI_0	CS5	—
		FlexPWM_0	—	FAULT[3]
M4	Not connected	—		
M6	V_{DD_LV}	—		
M7	V_{DD_LV}	—		
M8	V_{DD_LV}	—		
M9	V_{DD_LV}	—		
M10	V_{DD_LV}	—		
M11	V_{DD_LV}	—		
M12	V_{DD_LV}	—		
M14	C[11]	SIUL	GPIO[43]	GPIO[43]
		eTimer_0	ETC[4]	ETC[4]
		DSPI_2	CS2	—
M15	B[5]	SIUL	GPIO[21]	GPIO[21]
		JTAGC	—	TDI
M16	TMS	—		
M17	H[5]	SIUL	GPIO[117]	GPIO[117]
		FlexPWM_1	A[0]	A[0]
		DSPI_0	CS4	—
N1	XTAL	—		
N2	$V_{SS\_HV\_IO\_RING}$	—		
N3	D[5]	SIUL	GPIO[53]	GPIO[53]
		DSPI_0	CS3	—
		FlexPWM_0	—	FAULT[2]
N4	$V_{SS\_LV\_PLL0\_PLL1}$	—		

Table 8. Pin muxing (continued)

Port name	PCR	Peripheral	Alternate output function	Output mux sel	Input functions	Input mux select	Weak pull config during reset	Pad speed(1)		Pin #		
								SRC = 1	SRC = 0	100 pkg	144 pkg	257 pkg
F[7]	PCR[87]	SIUL	GPIO[87]	ALT0	GPIO[87]	—	—	F	S	—	19	J1
		NPC	MCKO	ALT2	—	—						
F[8]	PCR[88]	SIUL	GPIO[88]	ALT0	GPIO[88]	—	—	F	S	—	20	K2
		NPC	MSEO[1]	ALT2	—	—						
F[9]	PCR[89]	SIUL	GPIO[89]	ALT0	GPIO[89]	—	—	F	S	—	23	K1
		NPC	MSEO[0]	ALT2	—	—						
F[10]	PCR[90]	SIUL	GPIO[90]	ALT0	GPIO[90]	—	—	F	S	—	24	L1
		NPC	EVTO	ALT2	—	—						
F[11]	PCR[91]	SIUL	GPIO[91]	ALT0	GPIO[91]	—	—	M	S	—	25	L2
		NPC	—	ALT2	EVTI	—						
F[12]	PCR[92]	SIUL	GPIO[92]	ALT0	GPIO[92]	—	—	M	S	—	106	C17
		eTimer_1	ETC[3]	ALT1	ETC[3]	PSMI[12]; PADSEL=2						
		SIUL	—	—	EIRQ[30]	—						
F[13]	PCR[93]	SIUL	GPIO[93]	ALT0	GPIO[93]	—	—	M	S	—	112	B14
		eTimer_1	ETC[4]	ALT1	ETC[4]	PSMI[13]; PADSEL=3						
		SIUL	—	—	EIRQ[31]	—						
F[14]	PCR[94]	SIUL	GPIO[94]	ALT0	GPIO[94]	—	—	M	S	—	115	C13
		LINFlexD_1	TXD	ALT1	—	—						
F[15]	PCR[95]	SIUL	GPIO[95]	ALT0	GPIO[95]	—	—	M	S	—	113	D13
		LINFlexD_1	—	—	RXD	PSMI[32]; PADSEL=2						

3.5 Thermal characteristics

Table 12. Thermal characteristics for LQFP100 package(1)

Symbol		Parameter	Conditions	Value	Unit
$R_{\theta JA}$	D	Thermal resistance, junction-to-ambient natural convection(2)	Single layer board – 1s	46	°C/W
			Four layer board – 2s2p	34	
$R_{\theta JMA}$	D	Thermal resistance, junction-to-ambient forced convection at 200 ft/min	Single layer board – 1s	36	°C/W
			Four layer board – 2s2p	28	
$R_{\theta JB}$	D	Thermal resistance junction-to-board(3)	—	19	°C/W
$R_{\theta JC}$	D	Thermal resistance junction-to-case(4)	—	8	°C/W
Ψ_{JT}	D	Junction-to-package-top natural convection(5)	—	2	°C/W

1. Junction temperature is a function of die size, on-chip power dissipation, package thermal resistance, mounting site (board) temperature, ambient temperature, air flow, power dissipation of other components on the board, and board thermal resistance.
2. Junction-to-Ambient thermal resistance determined per JEDEC JESD51-3 and JESD51-6. Thermal test board meets JEDEC specification for this package.
3. Junction-to-Board thermal resistance determined per JEDEC JESD51-8. Thermal test board meets JEDEC specification for the specified package.
4. Junction-to-Case at the top of the package determined using MIL-STD 883 Method 1012.1. The cold plate temperature is used for the case temperature. Reported value includes the thermal resistance of the interface layer.
5. Thermal characterization parameter indicating the temperature difference between the package top and the junction temperature per JEDEC JESD51-2. When Greek letters are not available, the thermal characterization parameter is written as Psi-JT.

Table 13. Thermal characteristics for LQFP144 package(1)

Symbol		Parameter	Conditions	Value	Unit
$R_{\theta JA}$	D	Thermal resistance, junction-to-ambient natural convection(2)	Single layer board – 1s	44	°C/W
			Four layer board – 2s2p	36	
$R_{\theta JMA}$	D	Thermal resistance, junction-to-ambient forced convection at 200 ft/min	Single layer board – 1s	35	°C/W
			Four layer board – 2s2p	30	
$R_{\theta JB}$	D	Thermal resistance junction-to-board(3)	—	24	°C/W
$R_{\theta JC}$	D	Thermal resistance junction-to-case(4)	—	8	°C/W
Ψ_{JT}	D	Junction-to-package-top natural convection(5)	—	2	°C/W

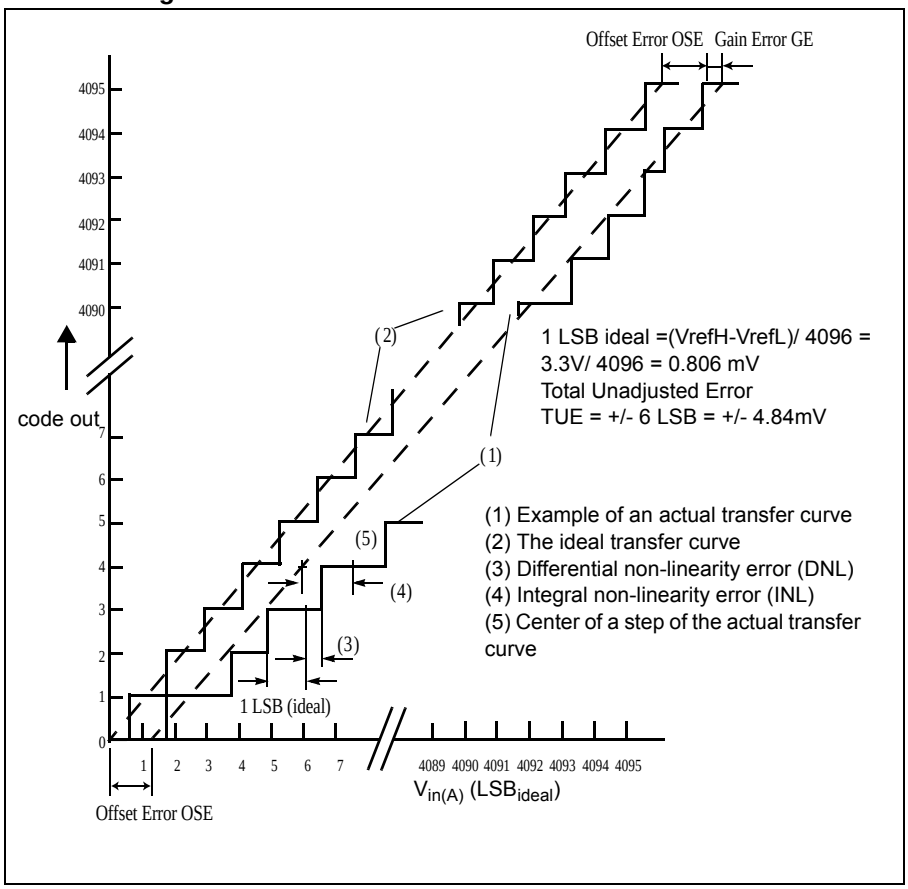
1. Junction temperature is a function of die size, on-chip power dissipation, package thermal resistance, mounting site (board) temperature, ambient temperature, air flow, power dissipation of other components on the board, and board thermal resistance.
2. Junction-to-Ambient thermal resistance determined per JEDEC JESD51-3 and JESD51-6. Thermal test board meets JEDEC specification for this package.
3. Junction-to-Board thermal resistance determined per JEDEC JESD51-8. Thermal test board meets JEDEC specification for the specified package.
4. Junction-to-Case at the top of the package determined using MIL-STD 883 Method 1012.1. The cold plate temperature is used for the case temperature. Reported value includes the thermal resistance of the interface layer.
5. Thermal characterization parameter indicating the temperature difference between the package top and the junction temperature per JEDEC JESD51-2. When Greek letters are not available, the thermal characterization parameter is written as Psi-JT.

Table 21. DC electrical characteristics(1) (continued)

Symbol		Parameter	Conditions	Min	Typ	Max	Unit
V_{OL_S}	P	Slow, low level output voltage	I_{OL} = 1.5 mA	—	—	0.5	V
V_{OH_S}	P	Slow, high level output voltage	I_{OH} = -1.5 mA	$V_{DD\_HV\_IOx}$ - 0.8	—	—	V
V_{OL_M}	P	Medium, low level output voltage	I_{OL} = 2 mA	—	—	0.5	V
V_{OH_M}	P	Medium, high level output voltage	I_{OH} = -2 mA	$V_{DD\_HV\_IOx}$ - 0.8	—	—	V
V_{OL_F}	P	Fast, high level output voltage	I_{OL} = 11 mA	—	—	0.5	V
V_{OH_F}	P	Fast, high level output voltage	I_{OH} = -11 mA	$V_{DD\_HV\_IOx}$ - 0.8	—	—	V
V_{OL_SYM}	P	Symmetric, high level output voltage	I_{OL} = 1.5 mA	—	—	0.5	V
V_{OH_SYM}	P	Symmetric, high level output voltage	I_{OH} = -1.5 mA	$V_{DD\_HV\_IOx}$ - 0.8	—	—	V
I_{INJ}	T	DC injection current per pin (all bi-directional ports)	—	–1	—	1	mA
I_{PU}	P	Equivalent pull-up current	$V_{IN} = V_{IL}$	–130	—	—	µA
			$V_{IN} = V_{IH}$	—	—	–10	
I_{PD}	P	Equivalent pull-down current	$V_{IN} = V_{IL}$	10	—	—	µA
			$V_{IN} = V_{IH}$	—	—	130	
I_{IL}	P	Input leakage current (all bidirectional ports)	T_J = -40 to +150 °C	-1	—	1	µA
		Input leakage current (all ADC input-only ports)(4)		-0.25	—	0.25	
		Input leakage current (shared ADC input-only ports)		-0.3	—	0.3	
V_{ILR}	P	$\overline{\text{RESET}}$, low level input voltage	—	–0.1(2)	—	0.35 $V_{DD\_HV\_IOx}$	V
V_{IHR}	P	$\overline{\text{RESET}}$, high level input voltage	—	0.65 $V_{DD\_HV\_IOx}$	—	$V_{DD\_HV\_IOx}$+0.1(2)	V
V_{HYSR}	D	$\overline{\text{RESET}}$, Schmitt trigger hysteresis	—	0.1 $V_{DD\_HV\_IOx}$	—	—	V
V_{OLR}	D	$\overline{\text{RESET}}$, low level output voltage	I_{OL} = 2 mA	—	—	0.5	V
I_{PD}	D	$\overline{\text{RESET}}$, equivalent pull-down current	$V_{IN} = V_{IL}$	10	—	—	µA
			$V_{IN} = V_{IH}$	—	—	130	

1. These specifications are design targets and subject to change per device characterization.

Figure 9. ADC characteristics and error definitions



3.16.1 Input Impedance and ADC Accuracy

To preserve the accuracy of the A/D converter, it is necessary that analog input pins have low AC impedance. Placing a capacitor with good high frequency characteristics at the input pin of the device can be effective: the capacitor should be as large as possible, ideally infinite. This capacitor contributes to attenuating the noise present on the input pin; further, it sources charge during the sampling phase, when the analog signal source is a high-impedance source.

A real filter can typically be obtained by using a series resistance with a capacitor on the input pin (simple RC filter). The RC filtering may be limited according to the value of source impedance of the transducer or circuit supplying the analog signal to be measured. The filter at the input pins must be designed taking into account the dynamic characteristics of the input signal (bandwidth) and the equivalent input impedance of the ADC itself.

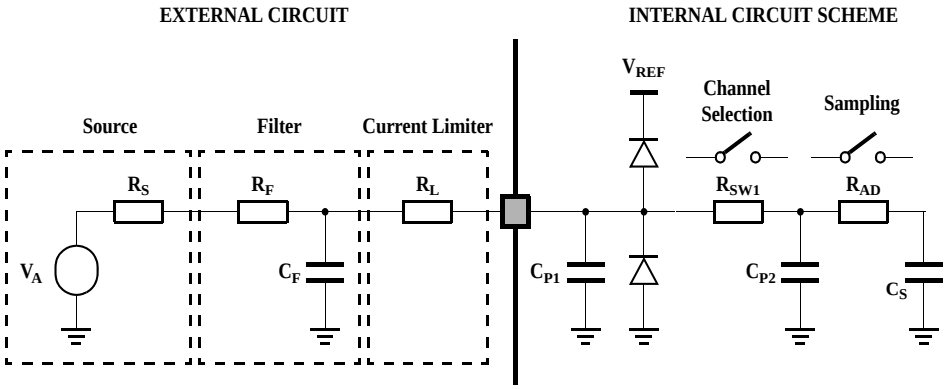
In fact a current sink contributor is represented by the charge sharing effects with the sampling capacitance: C_S and C_{p2} being substantially a switched capacitance, with a frequency equal to the conversion rate of the ADC, it can be seen as a resistive path to ground. For instance, assuming a conversion rate of 1 MHz, with C_{p2} + CS equal to 7.5 pF, a resistance of 133 kΩ is obtained (R_{EQ} = 1 / (fS*(C_{p2}+C_S)), where fS represents the conversion rate at the considered channel). To minimize the error induced by the voltage partitioning between this resistance (sampled voltage on C_s) and the sum of R_S + R_F, the external circuit must be designed to respect the *Equation 4*:

Equation 4:

$$V_A \bullet \frac{R_S + R_F}{R_{EQ}} < \frac{1}{2} LSB$$

Equation 4 generates a constraint for external network design, in particular on resistive path. Internal switch resistances (R_{SW} and R_{AD}) can be neglected with respect to external resistances.

Figure 10. Input Equivalent Circuit



Legend:

R_S Source Impedance

R_F Filter Resistance

C_F Filter Capacitance

R_L Current Limiter Resistance

R_{SW1} Channel Selection Switch Impedance

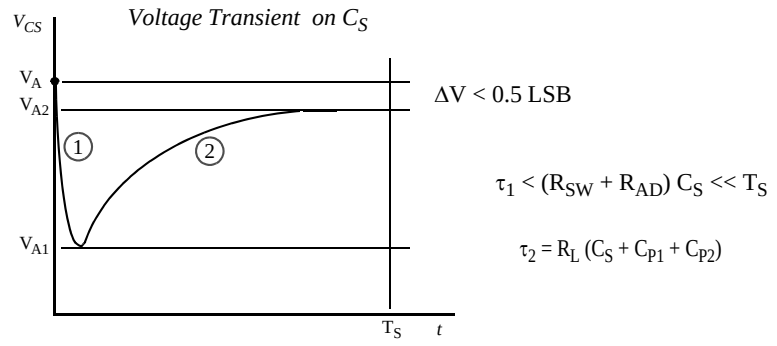
R_{AD} Sampling Switch Impedance

C_P Pin Capacitance (two contributions, C_{P1} and C_{P2})

C_S Sampling Capacitance

A second aspect involving the capacitance network shall be considered. Assuming the three capacitances C_F, C_{P1} and C_{P2} are initially charged at the source voltage V_A (refer to the equivalent circuit reported in *Figure 10*): A charge sharing phenomenon is installed when the sampling phase is started (A/D switch close).

Figure 11. Transient Behavior during Sampling Phase



In particular two different transient periods can be distinguished:

- A first and quick charge transfer from the internal capacitance C_{P1} and C_{P2} to the sampling capacitance C_S occurs (C_S is supposed initially completely discharged): considering a worst case (since the time constant in reality would be faster) in which C_{P2} is reported in parallel to C_{P1} (call $C_P = C_{P1} + C_{P2}$), the two capacitances C_P and C_S are in series, and the time constant is

Equation 5

$$\tau_1 = (R_{SW} + R_{AD}) \bullet \frac{C_P \bullet C_S}{C_P + C_S}$$

Equation 5 can again be simplified considering only C_S as an additional worst condition. In reality, the transient is faster, but the A/D converter circuitry has been designed to be robust also in the very worst case: the sampling time T_S is always much longer than the internal time constant:

Equation 6

$$\tau_1 < (R_{SW} + R_{AD}) \bullet C_S \ll T_S$$

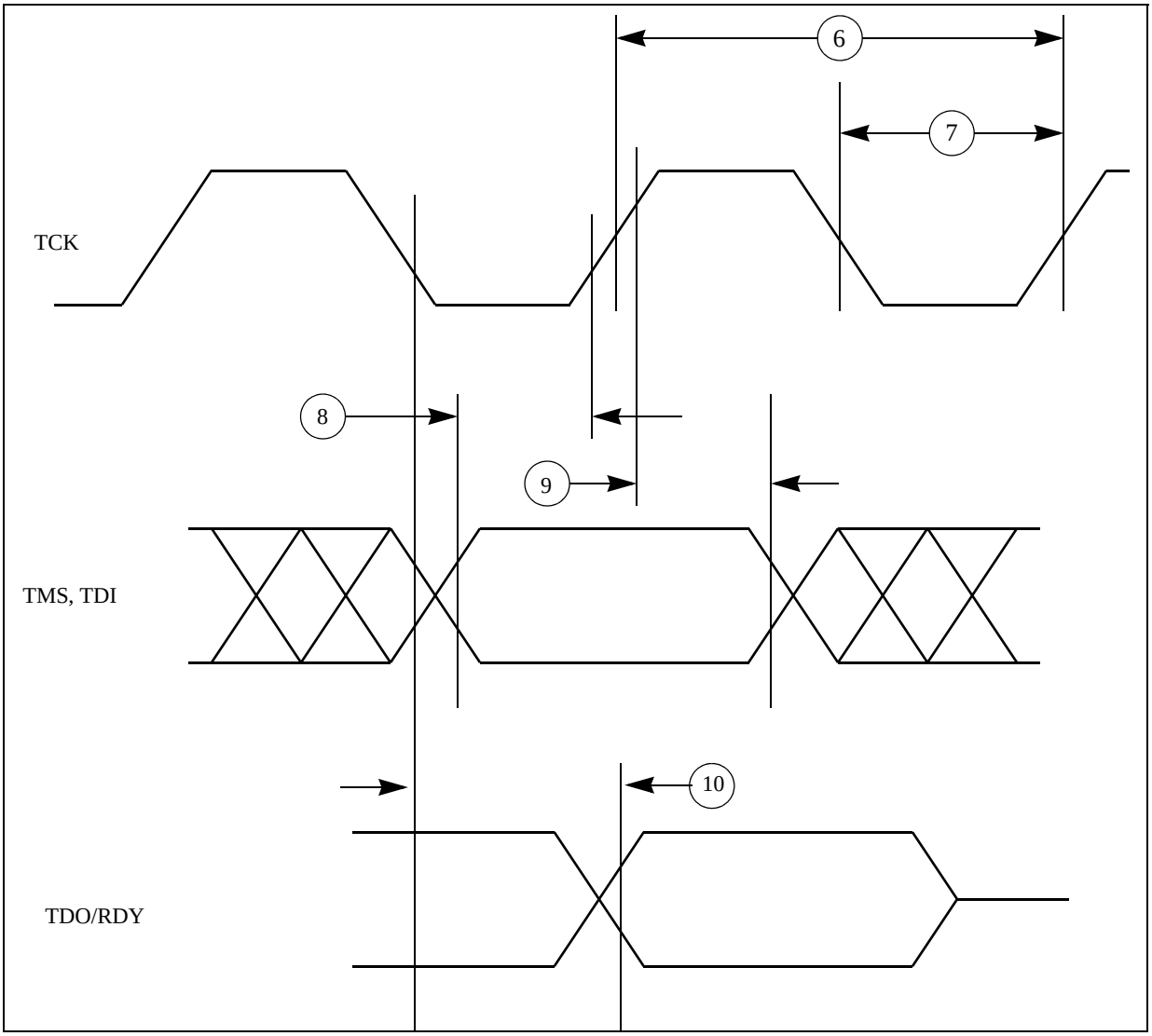
The charge of C_{P1} and C_{P2} is redistributed also on C_S, determining a new value of the voltage V_{A1} on the capacitance according to *Equation 7*:

Equation 7

$$V_{A1} \bullet (C_S + C_{P1} + C_{P2}) = V_A \bullet (C_{P1} + C_{P2})$$

- A second charge transfer involves also C_F (that is typically bigger than the on-chip capacitance) through the resistance R_L: again considering the worst case in which C_{P2}

Figure 30. Nexus TDI, TMS, TDO timing



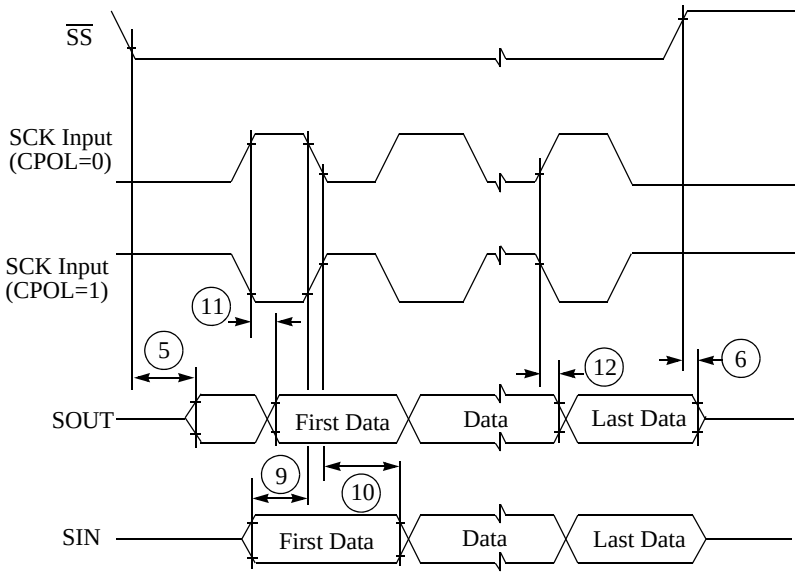
3.21.5 External interrupt timing (IRQ pin)

Table 40. External interrupt timing

No.	Symbol		Parameter	Conditions	Min	Max	Unit
1	t_{IPWL}	D	IRQ pulse width low	—	3	—	t_{CYC}
2	t_{IPWH}	D	IRQ pulse width high	—	3	—	t_{CYC}
3	t_{ICYC}	D	IRQ edge to edge time(1)	—	6	—	t_{CYC}

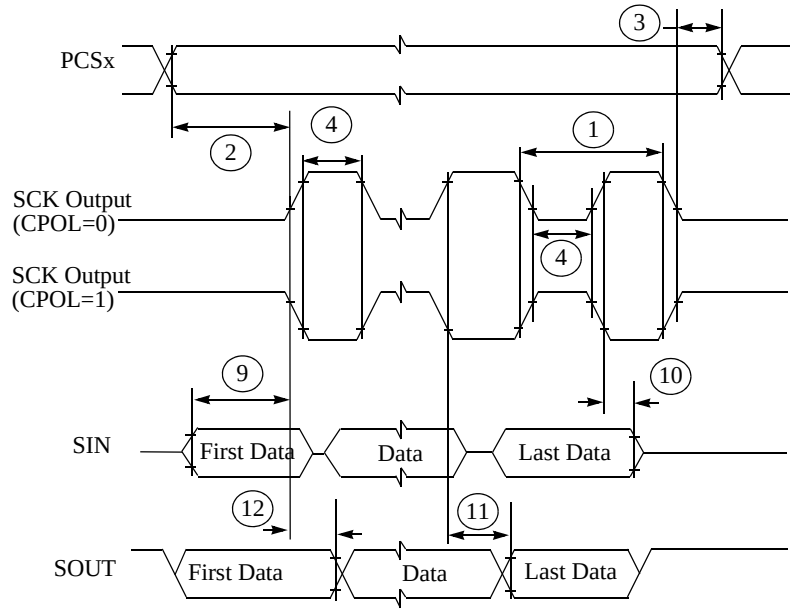
1. Applies when IRQ pins are configured for rising edge or falling edge events, but not both.

Figure 35. DSPI classic SPI timing — slave, CPHA = 1



Note: The numbers shown are referenced in *Table 41*.

Figure 36. DSPI modified transfer format timing — master, CPHA = 0



Note: The numbers shown are referenced in *Table 41*.

Table 42. LQFP100 mechanical data

Symbol	mm			inches[1]		
	Min	Typ	Max	Min	Typ	Max
A	—	—	1.600	—	—	0.0630
A1	0.050	—	0.150	0.0020	—	0.0059
A2	1.350	1.400	1.450	0.0531	0.0551	0.0571
b	0.170	0.220	0.270	0.0067	0.0087	0.0106
c	0.090	—	0.200	0.0035	—	0.0079
D	15.800	16.000	16.200	0.6220	0.6299	0.6378
D1	13.800	14.000	14.200	0.5433	0.5512	0.5591
D3	—	12.000	—	—	0.4724	—
E	15.800	16.000	16.200	0.6220	0.6299	0.6378
E1	13.800	14.000	14.200	0.5433	0.5512	0.5591
E3	—	12.000	—	—	0.4724	—
e	—	0.500	—	—	0.0197	—
L	0.450	0.600	0.750	0.0177	0.0236	0.0295
L1	—	1.000	—	—	0.0394	—
k	0.0 °	3.5 °	7.0 °	0.0 °	3.5 °	7.0 °
Tolerance	mm			inches		
ccc	0.080			0.0031		

1. Values in inches are converted from mm and rounded to 4 decimal digits.

Table 45. Document revision history

Date	Revision	Changes
01-Aug-2012	8	Editorial changes. In the “Block diagram” section, removed one PMU from the figure. In the 257-pin pinout figure, changed cut2 to cut2/3 in Notes. In the pin function summary table, changed cut2 to cut2/3. In the “System pins” table: – Added Note regarding Open Drain Enable. – Added description to RESET pin. In the pin-muxing table: – Added Note about Open Drain. – Changed cut2 to cut2/3. – Changed all entries of column 'Weak pull config during reset’ to ' - ' , except for PCR[2], PCR[3], PCR[4] and PCR[21]. In the “Absolute maximum ratings” table: – Removed the “$V_{SS\_HV\_REG}$” row. – Added the footnote “Internal structures hold the input voltage...” to the V_{IN} maximum specifications. In the “Recommended operating conditions” table, removed the “$V_{SS\_HV\_REG}$” row. In the “Thermal characteristics” section: – Added the “Thermal characteristics for LQFP100 package“ table. – Updated values and footnote 1 in the 144 package table. – Updated footnote 1 in the 257 package table. In the “Supply current characteristics“ table: – Added footnote 1 to parameter “$I_{DD\_LV\_TYP}$ + $I_{DD\_LV\_PLL}$“ (symbol “T”). – Changed “$I_{DD\_LV\_STOP}$” at 150C from 80mA to 72mA. – Changed “$I_{DD\_LV\_HALT}$” at 150C from 72mA to 80mA. In the “FMPLL electrical characteristics” table: – Deleted the footnote “This value is true when operating at frequencies above 60 MHz...” from the specification for f_{CS} and f_{DS}. – Changed “f_{SYS}” to “$f_{FMPLLOUT}$” in the entries for the C_{JITTER}, f_{LCK}, f_{UL}, f_{CS}, and f_{DS} specifications. In the “ADC conversion characteristics” table: – Revised the entry for $TUE_{IS1WINJ}$ (was P/T and “Total unadjusted error for IS1WINJ”, is T and “Total unadjusted error for IS1WINJ (single ADC channels)”). – Revised the entry for $TUE_{IS1WWINJ}$ (was “Total unadjusted error for IS1WWINJ”, is “Total unadjusted error for IS1WWINJ (double ADC channels)”). In the “Temperature sensor electrical characteristics“ table, for T_J = T_A to 125 °C, changed Min/Max from values -7/+7 to -10/+10. In the “Input Impedance and ADC Accuracy“ section: – Changed C_S in the text from 3 pF to 7.5 pF. – Changed R_{eq} in the text from 330 kΩ to 133 kΩ. – Removed R_L, R_{SW}, and R_{AD} from the external network design constraint equation and the sentence immediately preceding it. – Changed the C_F constraint value equation constant from 2048 to 8192. In the “ADC conversion characteristics“ table, changed INL Min/Max values from -2/+2 to -3/+3.